JSCJ

MSDS Report

Report NO.: MG00001000004

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAE28SN06
Package Type :	DFNWB3x3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.59%
Lead Frame	Copper	7440-50-8	92.46%	53.86%
	Iron	7439-89-6	2.50%	
	Lead	7439-92-1	0.01%	
	Phosphorus	7723-14-0	0.02%	
	Zinc	7440-66-6	0.02%	
	Silver	7440-22-4	5.00%	
Die Attach	Silver	7440-22-4	80.000%	3.62%
	bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ⩽ 700) (old)	9003-36-5	12.000%	
	1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	6.500%	
	dapsone	80-08-0	1.500%	
Wire	Cu	7440-50-8	97.70%	0.08%
	Pd	7440-05-3	2.30%	
Mold Compound	Epoxy Resin1	Trade secret	3.00%	31.85%
	Epoxy Resin2	Trade secret	3.00%	
	Phenolic Resin	Trade secret	5.00%	
	catalyst	Trade secret	0.50%	
	Carbon Black	1333-86-4	0.30%	
	Amorphous silica 1	60676-86-0	80.00%	
	Amorphous silica 2	7631-86-9	8.20%	
Plating	Tin	7440-31-5	100.00%	9.00%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.